nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Nexperia B.V. SZMM3Z18VT1G-Q Name of Laboratory Part Description Assembly reliability labs SMD package Based on AEC-Q101 Test Test Conditions Duration # Loc rEST Pre- and Post-Stress Tamb = 25 °C N/A see I # E1 Electrical Test Tamb = 25 °C N/A see I PC Soak Tamb = 125 °C 24 hours 168 hours # A1 Preconditioning Reflow soldering 3 cycles 1514 # A1 Preconditioning Reflow soldering 3 cycles 1514 # B1 Bias voltage 1000 hours 250 # B1 Bias voltage 1000 hours 250 # B1b Steady State Operational reverse current 1000 hours 44	4 Oursette	
Assembly reliability labs SMD package Based on AEC-Q101 Test Test Orditions Duration # Lo TEST Pre- and Post-Stress # E1 Electrical Test Tamb = 25 °C N/A see I JESD22-A113 Bake Tamb = 125 °C 24 hours Bake Tamb = 125 °C 24 hours 168 hours 3 Bake Tamb = 85 °C, RH = 85% 168 hours 168 hours 3 C, RH = 85% 168 hour	4 Quan ¹¹	
Assembly reliability labs SMD package Based on AEC-Q101 Test Test Conditions Duration # Lo TEST Pre- and Post-Stress # E1 Electrical Test Tamb = 25 °C N/A see I ESD22-A113 Bake Tamb = 125 °C 24 hours Bake Tamb = 125 °C 24 hours Bake Tamb = 125 °C 24 hours Bake Tamb = 85 °C, RH = 85% 168 hours FC Soak Tamb = 85 °C, RH = 85% 168 hours A 10 Preconditioning Reflow soldering 3 cycles 1514 MIL-STD-750-1 HTRB M1038 Method A High Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse # B1 Bias voltage 1000 hours 250 MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet	to # 0.000	
Based on AEC-Q101 Test Test Conditions Duration # Lo TEST Pre- and Post-Stress Pre- and Post-Stress N/A see I # E1 Electrical Test Tamb = 25 °C N/A see I JESD22-A113 Bake Tamb = 125 °C 24 hours Soak Tamb = 125 °C 24 hours # A1 Preconditioning Reflow soldering 3 cycles 1514 MIL-STD-750-1 MIL-STD-750-1 HTRB M1038 Method A High Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse 1000 hours 250 MIL-STD-750-1 M1038 Method B Tj = Tjmax, Iz = 100% of max. datasheet	4 Ouentite	
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HTRB M1038 Method A High Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse # B1 Bias voltage 1000 hours 250 MIL-STD-750-1 M1038 Method B SSOP Tj = Tjmax, Iz = 100% of max. datasheet	64430	0
M1038 Method B SSOP Tj = Tjmax, Iz = 100% of max. datasheet	11400	0
	1920	0
TC JESD22-A104 # A4 Temperature Cycling -65 °C to Tjmax, not to exceed 150°C 1000 cycles 311	14080	0
UHAST JESD22-A118 # A3 or Unbiased HAST Tamb = 130 °C, RH = 85 % OC human 211	14000	0
AC JESD22-A102 96 hours 311 # A3 alt Autoclave Pressure = 205 kPa (29.7 psia) 96 hours 311	14080	0
H3TRB JESD22-A101 High Humidity High Tamb = 85 °C, RH = 85%, VR = 80 % of # A2 alt Temperature Reverse Bias rated reverse voltage ^[1] 1000 hours 311	14080	0
MIL-STD-750 Method 1037 IOL ton = toff, devices powered to insure ΔTj = # A5 Intermittent Operating Life 100 °C for 15000 cycles 1000 hours 312	14120	0
RSH JESD22-A111 # C8 Resistance to Solder Heat 260 °C ± 5 °C 10 s 269		
# C8 Resistance to Solder Heat 260 °C ± 5 °C 10 s 269 SD # C10 Solderability J-STD-002 19	8070	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

2,68E+09
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